

## Electronic Acknowledgement Receipt

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Application Number:	10731995
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Title of Invention:	PACKAGES FOR SEMICONDUCTOR DIE
First Named Inventor:	Todd O. Bolken
Customer Number:	23720
Filer:	J. Mike Amerson/Mary Paul
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### File Listing:

Document Number	Document Description	File Name	File Size(Bytes)	Multi Part	Pages
1	Issue Fee Payment Recorded	Fees_Transmittal.pdf	63479	no	1

Warnings:	
Information:	
Total Files Size (in bytes):	63479
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